ne<mark>x</mark>peria

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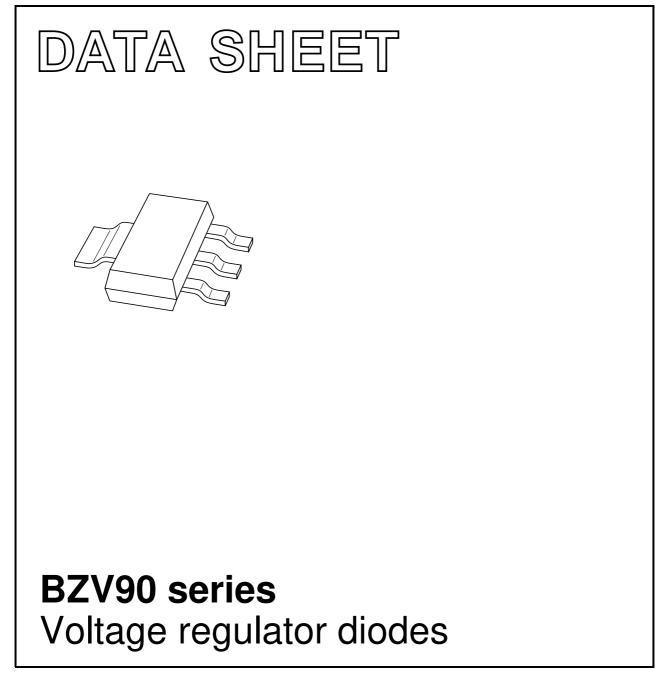
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If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 1996 Oct 25 1999 May 17



BZV90 series

FEATURES

- Total power dissipation: max. 1500 mW
- Tolerance series: approx. ±5%
- Working voltage range: nom. 2.4 to 75 V (E24 range)
- Non-repetitive peak reverse power dissipation: max. 40 W.

APPLICATIONS

• General regulation functions.

DESCRIPTION

Medium-power voltage regulator diodes in SOT223 plastic SMD packages.

The diodes are available in the normalized E24 approx. $\pm 5\%$ tolerance range. The series consists of 37 types with nominal working voltages from 2.4 to 75 V (BZV90-C2V4 to C75).

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _F	continuous forward current		-	400	mA
I _{ZSM}	non-repetitive peak reverse current	$t_p = 100 \ \mu s$; square wave; T _j = 25 °C prior to surge	see Table "Per type"		
P _{tot}	total power dissipation	T _{amb} = 25 °C; note 1	-	1500	mW
P _{ZSM}	non-repetitive peak reverse power dissipation	t_p = 100 µs; square wave; T _j = 25 °C prior to surge; see Fig.2	_	40	W
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C

Note

1. Device mounted on an FR4 double-sided copper-clad printed circuit-board; copper area = 2 cm².

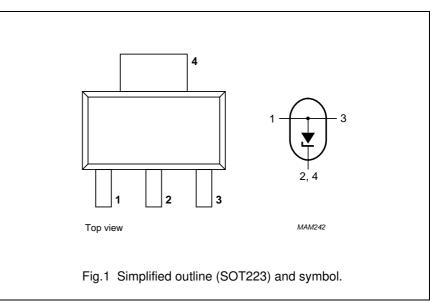
ELECTRICAL CHARACTERISTICS

Total series

 $T_i = 25 \ ^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _F	forward voltage	$I_F = 50 \text{ mA}; \text{ see Fig.3}$	_	1.0	V

PIN	DESCRIPTION			
1	anode			
2, 4	cathode			
3	anode			



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Product data sheet

BZV90 series

DIODE CAP. TEST REVERSE WORKING DIFFERENTIAL TEMP. COEFF. NON-REPETITIVE PEAK CURRENT VOLTAGE RESISTANCE S_Z (mV/K) C_d (pF) **CURRENT** at **REVERSE CURRENT** $V_{Z}(V)$ r_{dif} (Ω) at Iztest I_{Ztest} (mA) at f = 1 MHz; REVERSE I_{ZSM} (A) **BZV90**see Figs 4 and 5 at $V_B = 0 V$ VOLTAGE at $t_p = 100 \ \mu s$; at Iztest at Iztest CXXX T_{amb} = 25 °C **I_B (μA)** VR (V) MIN. TYP. MIN. MAX. TYP. MAX. MAX. MAX. MAX. MAX. 2V4 2.2 2.6 70 100 -3.5 -1.60 5 450 50 1.0 6.0 2V7 2.5 2.9 75 100 -3.5-2.0 0 5 450 20 1.0 6.0 3V0 2.8 3.2 80 95 -3.5 -2.1 0 5 450 10 1.0 6.0 -2.4 3V3 3.1 3.5 85 95 -3.5 0 5 450 5 1.0 6.0 -2.4 5 5 3V6 3.4 3.8 85 90 -3.5 0 450 1.0 6.0 -2.5 3V9 5 3 3.7 4.1 85 90 -3.5 0 450 1.0 6.0 5 3 4V3 4.0 4.6 80 90 -3.5 -2.5 0 450 1.0 6.0 4V7 4.4 5.0 50 80 -3.5 -1.4 0.2 5 300 3 2.0 6.0 2 5V1 4.8 5.4 40 60 -2.7 -0.81.2 5 300 2.0 6.0 5.2 5V6 6.0 15 40 -2.0 1.2 2.5 5 300 1 2.0 6.0 6V2 5.8 6.6 6 2.3 3.7 5 200 3 4.0 6.0 10 0.4 6V8 6.4 7.2 6 1.2 3.0 4.5 5 200 2 4.0 6.0 15 7V5 5 1 7.0 7.9 6 2.5 4.0 5.3 150 5.0 4.0 15 7.7 8.7 6.2 5 150 0.7 4.0 8V2 6 15 3.2 4.6 5.0 9V1 8.5 9.6 6 15 5.5 7.0 5 150 0.5 6.0 3.0 3.8 5 0.2 7.0 10 9.4 10.6 8 20 4.5 6.4 8.0 90 3.0 11 10.4 11.6 10 20 5.4 7.4 9.0 5 85 0.1 8.0 2.5 12 5 11.4 12.7 10 25 6.0 8.4 10.0 85 0.1 8.0 2.5 13 12.4 14.1 10 30 7.0 9.4 11.0 5 80 0.1 8.0 2.5 15 75 5 2.0 13.8 15.6 10 30 9.2 11.4 13.0 0.05 10.5 16 75 15.3 17.1 10 40 10.4 12.4 14.0 5 0.05 11.2 1.5 18 16.8 19.1 14.4 16.0 5 70 0.05 12.6 1.5 10 45 12.4 20 60 1.5 5 18.8 21.2 15 55 14.4 16.4 18.0 0.05 14.0

1999 $T_j = 25 \circ C$

ω

Per type $T_j = 25 \text{ °C}$ unless otherwise specified.

BZV90- CXXX			∢)	TEST CURRENT I _{Ztest} (mA)	DIODE CAP. $C_d (pF)$ at f = 1 MHz; at V _R = 0 V	REVERSE CURRENT at REVERSE VOLTAGE		NON-REPETITIVE PEAK REVERSE CURRENT I_{ZSM} (A) at t _p = 100 μ s;				
•										I _R (μΑ)	V _R	T _{amb} = 25 °C
	MIN.	MAX.	TYP.	MAX.	MIN.	TYP.	MAX.		MAX.	MAX.	(V)	MAX.
22	20.8	23.3	20	55	16.4	18.4	20.0	5	60	0.05	15.4	1.25
24	22.8	25.6	25	70	18.4	20.4	22.0	5	55	0.05	16.8	1.25
27	25.0	28.9	25	80	21.4	23.4	25.3	2	50	0.05	18.9	1.0
30	28.0	32.0	30	80	24.4	26.6	29.4	2	50	0.05	21.0	1.0
33	31.0	35.0	35	80	27.4	29.7	33.4	2	45	0.05	23.1	0.9
36	34.0	38.0	35	90	30.4	33.0	37.4	2	45	0.05	25.2	0.8
39	37.0	41.0	40	130	33.4	36.4	41.2	2	45	0.05	27.3	0.7
43	40.0	46.0	45	150	37.6	41.2	46.6	2	40	0.05	30.1	0.6
47	44.0	50.0	50	170	42.0	46.1	51.8	2	40	0.05	32.9	0.5
51	48.0	54.0	60	180	46.6	51.0	57.2	2	40	0.05	35.7	0.4
56	52.0	60.0	70	200	52.2	57.0	63.8	2	40	0.05	39.2	0.3
62	58.0	66.0	80	215	58.8	64.4	71.6	2	35	0.05	43.4	0.3
68	64.0	72.0	90	240	65.6	71.7	79.8	2	35	0.05	47.6	0.25
75	70.0	79.0	95	255	73.4	80.2	88.6	2	35	0.05	52.5	0.2

BZV90 series

1999 May 17

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Product data sheet

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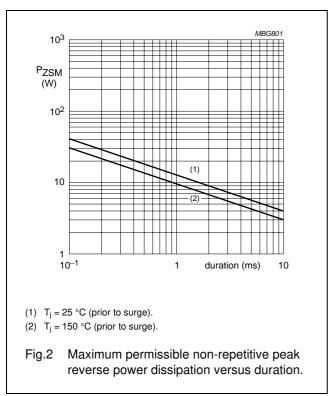
THERMAL CHARACTERISTICS

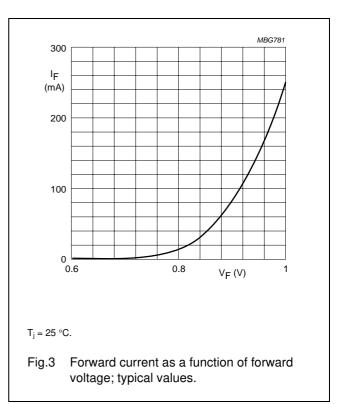
SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	lead length max.; note 1	83.3	K/W

Note

1. Device mounted on an FR4 double-sided copper-clad printed circuit-board; copper area = 2 cm².

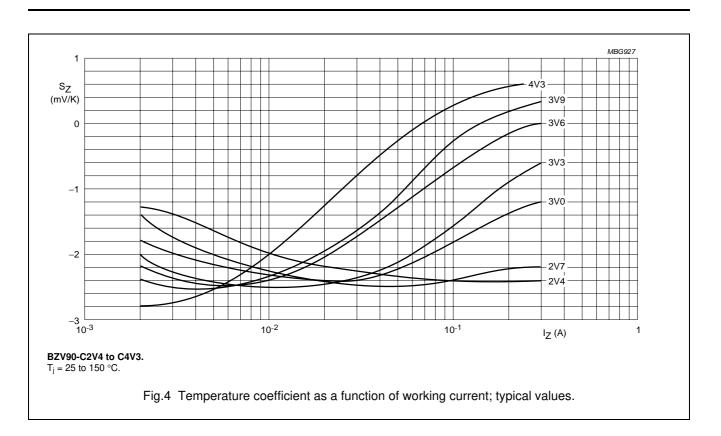
GRAPHICAL DATA

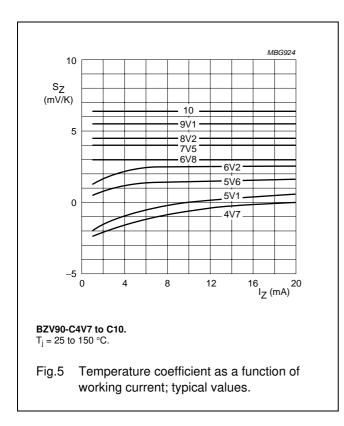




BZV90 series

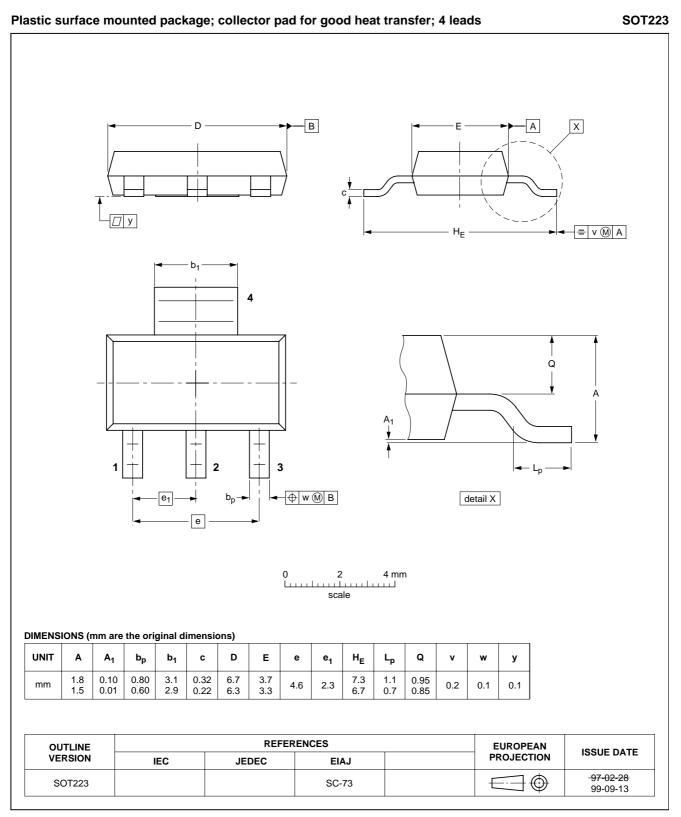
BZV90 series





BZV90 series

PACKAGE OUTLINE



BZV90 series

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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Printed in The Netherlands

115002/00/03/pp9

Date of release: 1999 May 17

Document order number: 9397 750 05928

